



XPC8240RX RELIABILITY DATA SUMMARY

XPC8240 - Kahlua - Information

Fab: MOS13, Austin, TX

Mask: J60F

Process: HiP3

Package: 352 pin TBGA

Assy: ASAT, HongKong

XC8240 - Kahlua - TECHNOLOGY: MOS13 on the 0.29 μ m HiP3 process

DYNAMIC LIFETEST (3.1V, 125°C)

168 HRS	504 HRS	1008 HRS	2016 HRS
0 / 231	0 / 231	0 / 231	/

ESD (HBM)

1KV	2KV
/	0 / 12

ESD (MM)

100V	200V
/	0 / 12

ESD (CDM)

500V	1KV
/	0 / 12

LATCHUP

150 mA	200 mA
0 / 3	0 / 12

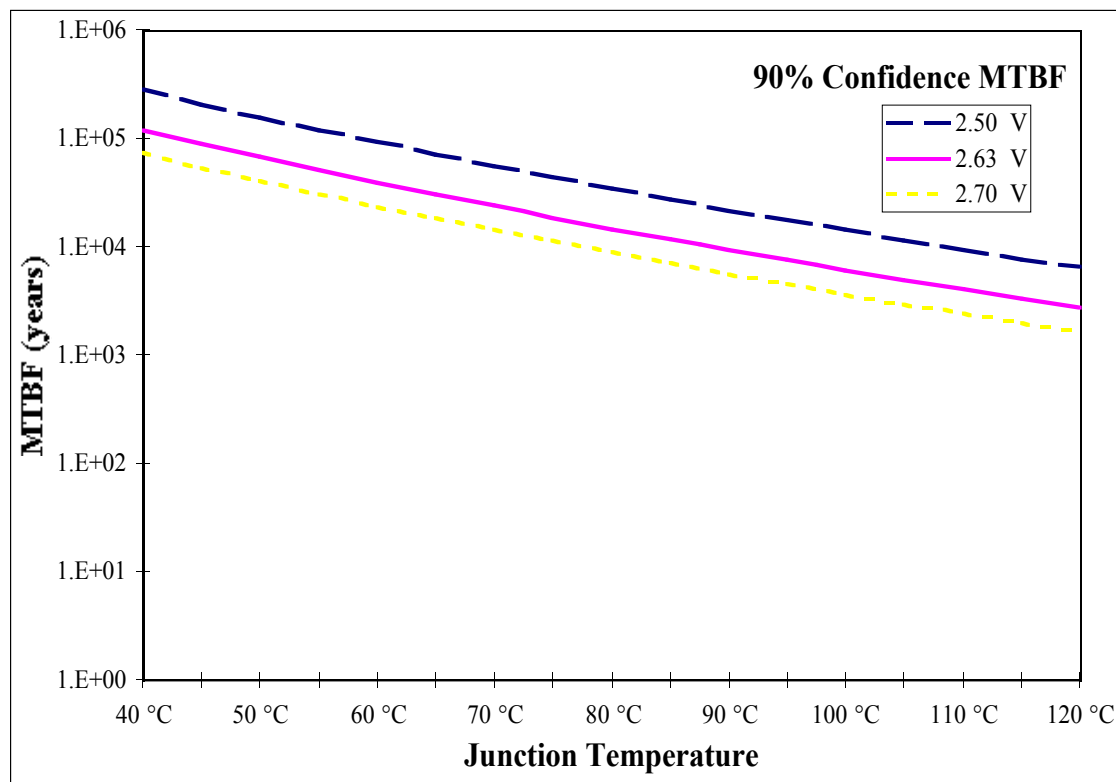
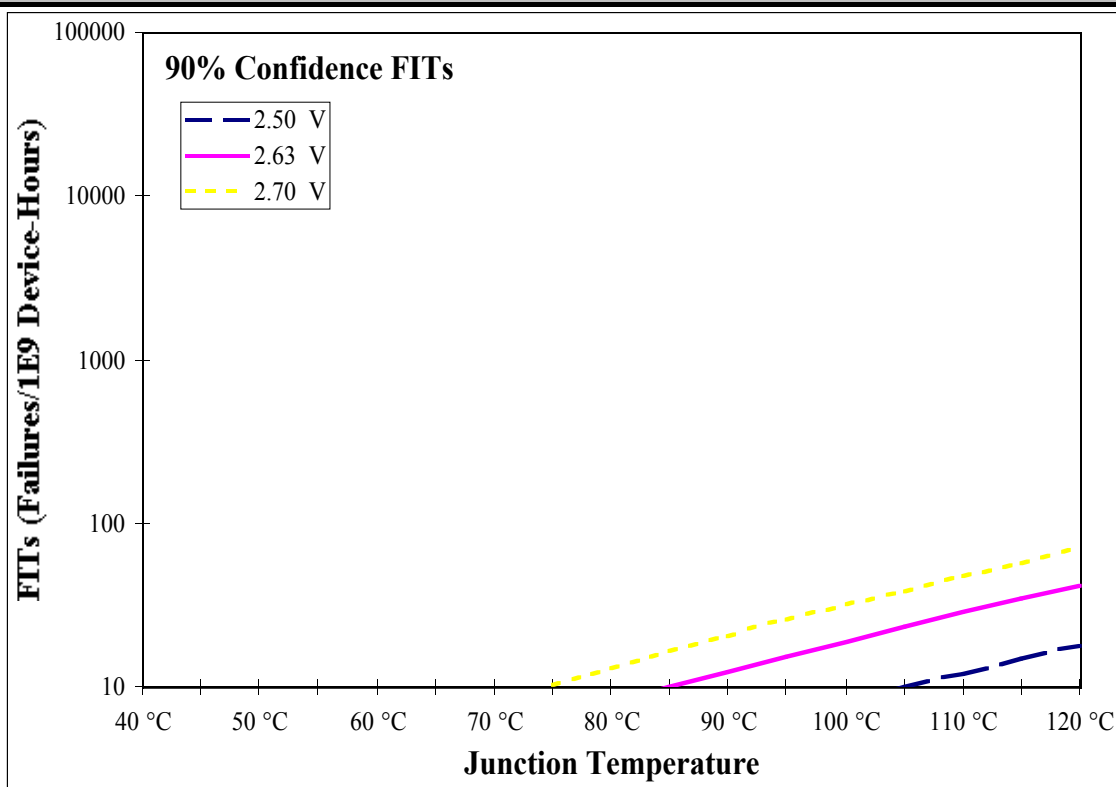
SUPPORTING TECHNOLOGY: HiP3 Summary for 3Q98-1Q01

DYNAMIC LIFETEST (3.1V, 125°C)

24 HRS	168 HRS	504 HRS	1008 HRS
0 / 3155	0 / 3155	0 / 2134	0 / 885

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TECHNOLOGY FAILURE RATES - HiP3





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PACKAGE: 352 Pin 35 x 35mm TBGA - ASAT
Data Summary 2Q99 - 1Q01

MOISTURE CZ

PRECOND MSL3	PRECOND MSL4
	0 / 90

TEMPERATURE CYCLING (-65°C/+150°C)

PRECOND MSL4	100 CYC	500 CYC	1000 CYC
0 / 924	0 / 924	0 / 924	231

THERMAL SHOCK (-55°C/+125°C)

PRECOND MSL4	100 CYC	500 CYC	1000 CYC
0 / 231	0 / 231	0 / 231	

AUTOCLAVE (+121°C, 100% RH, 2 atm)

PRECOND MSL4	48 HRS	144 HRS
0 / 693	4 / 693	0 / 0

Failure 48hr: 1 Short Fail

Failure 48hr: 3 Copper Fragment in DeBussing Hole - Corrective action implemented

THB (+85°C/85% RH/1.8V)

PRECOND MSL4	168 HRS	504 HRS	1008 HRS
0 / 462	0 / 462	0 / 462	

BAKE (175°C)

168 HRS	504 HRS
0 / 231	0 / 231